Joint International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP)

July 28 ~ 31, 2008, Shanghai, China

CALL FOR PAPERS

ABOUT ICEPT-HDP 2008

During last decade, both International Conference on Electronic Packaging Technology (ICEPT), organized by China Electronic Packaging Society, Chinese Institute of Electronics (CIE-CEPS), and International Symposium on High Density Packaging (HDP), organized by Shanghai University, have provided a great technical platform for both abroad and domestic experts, scholars and researchers from academia and industries to exchange the ideas in the new developments of electronics packaging. It has been decided IEEE-CPMT and CIE-CEPS, ICEPT and HDP are merged as International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP) this year in order to meet the requirements of rapidly growing packaging industry in China.

The ICEPT-HDP 2008 is a 4-day event which will be held from July 28 to July 31 of 2008 in Shanghai, China. The conference will feature short courses, keynotes and technical sessions to widely cover the technological developments in all the areas of electronics packaging.

CONFERENCE THEMES

You are invited to submit an abstract, describing new development in the following themes:

- **Advanced Packaging & System Integration**: BGA, CSP, flip chip; WLP, SoP, SiP; 3D packaging, PoP, TSV; micro- & nano-system packaging; and other advanced packaging and system integration technologies.
- **High Density Substrate & SMT:** Embedded passives and active components; micro-via, micro-join, HDI, PCB, high performance multi-layer substrate; stencil print, reflow; and other novel assembly technologies that improve substrate density and performance.
- **Packaging Design and Modeling:** Various new packaging/assembly designs; methods/technologies/software for modeling, simulation and validation of electrical, thermal, optical and mechanical performance of various electronics packages; chip-packaging-PCB co-design; and multi-function & scale modeling, simulation, validation methods/software.
- **Emerging Technologies:** Sensors, actuators, MEMS, NEMS & MOEMS; optoelectronics & LED packaging; LCD, passive & RF devices, power & HV devices; nano-devices based on nano-wires, nano-tubes and polymers, etc.
- **Packaging Materials & Processes:** New developments in bonding wires, solders, underfills, encapsulations, adhesives, thin films, dielectrics, substrate materials; green electronics materials, nanomaterials and other novel materials for packaging performance enhancement and cost reduction; and various packaging/assembly processes.
- **Packaging Equipment, Measurement & Characterization:** New packaging/assembly equipment; new methods/ technologies/systems for quality monitoring, process control, failure inspection, performance characterization, and deformation measurement; and packaging equipment/ measurement techniques for emerging technologies.
- **Advanced Manufacturing Technologies:** Photolithography, laser processing; novel packaging/assembly technologies for manufacturability and yield improvement, cost reduction and service performance improvement; and methods/software for modeling and monitoring of process effectiveness & cost analysis.
- **Quality & Reliability:** Quality monitoring and evaluation for packaging/assembly; advanced methods/technologies/tools for rapid reliability data collection/analysis, reliability modeling & life prediction; reliability issues in various electronics packages; and new methods/technologies/tools for failure analysis.

IMPORTANT DATES

- **April 11, 2008 – Submission of Abstract**
- **April 25, 2008 – Notification of Acceptance**
- **June 20, 2008 – Submission of Manuscript**

SUBMISSION OF ABSTRACT/PAPER

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, conclusions and important references of the work. All abstracts must be in English and should be submitted using the format provided in the attached word file through the email: icept2008@fudan.edu.cn.

The abstracts must be received by **April 11, 2008.** Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance by **April 25, 2008.** The final manuscript for publication in the conference proceedings is due by **June 20, 2008.** Selected papers will be recommended for publication in IEEE/CPMT journals.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components and software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may email icept2008@fudan.edu.cn for details.

General Chair	Executive Chair	Technical Chair	Organizing Chair
Mr. Keyun BI	Prof. Li JIN	Dr. Tom CHUNG	Prof. Xiaojing WU
CEPS, China	Fudan University, China	ASTRI, HK, China	Fudan University, China

Conference Website: http://www.icept.org **Conference Contacts: icept2008@fudan.edu.cn**

电子封装技术和高密度封装联合国际会议 (ICEPT-HDP)

2008 年 7 月 28 日 -- 31 日，上海，中国

征文通知

关于 ICEPT-HDP 2008

在过去十多年间，由中国电子学会生产技术学分会(CEPS)主办的电子封装技术(ICEPT)和上海大学主办的高密度封装(HDP)两个国际会议为来自海内外学术界和工业界的专家、学者和研究人员提供了一个交流电子封装技术新进展、新思路的重要技术平台。为了更好地满足中国快速发展的电子封装工业对于先进电子封装技术交流的需求，经国际电子与电气工程师协会电子元件封装和生产技术学分会(IEEE-CPMT)和中国电子学会生产技术学分会(CIE-CEPS)研究决定，自 2008 年起，电子封装技术(ICEPT)和高密度封装(HDP) 合并为电子封装技术和高密度封装国际会议(ICEPT-HDP)。

ICEPT-HDP 2008 是一个为期 4 天的国际会议，将于 2008 年 7 月 28 日 -- 31 日在中国上海举行。会议将通过专题讲座、特邀报告、主题论坛等形式对电子封装的各个技术领域中的最新进展进行交流。

会议主题

我们诚挚地邀请您针对下述主题投稿:

- **先进封装与系统封装:** 球栅阵列封装、芯片级封装、倒装芯片；晶圆级封装、系统封装、封装内系统；三维封装、堆叠封装、硅通孔；微纳米系统封装；及其它各种先进的封装和系统集成技术。
- **高密度基板及组装技术:** 嵌入式无源和有源元件；微孔洞、微连接、高密度互连、印刷电路板、高性能多层基板；丝网印刷、回流焊；及其它能够提高基板密度和性能的各种新型组装技术。
- **封装设计与模拟:** 各种新的封装/组装设计；对各种电子封装的电、热、光和机械特性进行建模、模拟和验证的方法/技术/软件；芯片-封装-印刷电路板的共同设计；多功能和多尺度的建模、模拟、验证方法及其软件技术。
- **新兴领域封装:** 传感器、执行器、微电机系统、纳电机系统、微光电机系统；光电子和发光二极管封装；液晶显示，无源元件，及射频、功率、高压器件；基于纳米线、纳米管、高分子聚合物的纳米器件等。
- **封装材料与工艺:** 键合丝、焊锡、芯片下填料、塑封料、粘接剂、薄膜材料、介电材料、基板材料和导热材料的最新进展；绿色电子材料、纳米材料和其它能够提高封装性能和降低成本的新型材料；以及各种各样的封装与组装工艺。
- **封装设备、测量及表征:** 新型的封装和组装制造设备；质量监控、工艺过程控制、可靠性检测、和变形测量相关的新方法/技术/设备；及针对新兴领域封装的相关封装设备/测量方法的进展。
- **先进制造技术:** 光刻、激光加工技术；提升可制造性和良品率、降低成本及改善使用可靠性的新型封装/组装技术；及用于工艺有效性模拟和监控，成本分析等相关的先进方法/软件。
- **质量与可靠性控制:** 封装/组装制造质量监视与质量评估；用于快速可靠性数据收集和分析，可靠性模拟和寿命预测的先进方法/技术/软件；新型领域封装技术中的相关可靠性问题；及新的失效分析的方法/技术/工具。

重要会议日期

- **投稿截止日期** 2008 年 4 月 11 日
- **投稿录用通知日期** 2008 年 4 月 25 日
- **论文全文截止日期** 2008 年 6 月 20 日

论文/摘要投稿

论文内容必须为具有原创性且没有发表过的技术成果。论文摘要须用大约 500 字的篇幅清楚地描述该项工作的背景、研究方法、结果、和结论，论文摘要还应包括关键的参考文献。论文摘要必须用英文、按所附电子模板的要求撰写，并以 word 或 PDF 文档通过电子邮件发送至 icept2008@fudan.edu.cn

论文摘要的投稿截止日期为 **2008 年 4 月 11 日**，来稿请注明您的联系方式，包括电子信箱、通讯地址、联系电话和传真。大会将于 **2008 年 4 月 25 日**前通知您论文的录用情况。论文全文必须于 **2008 年 6 月 20 日**收到，所有录用论文都将被收入 IEEE 会议论文集，优秀会议论文将被推荐到 IEEE-CPMT 的相关期刊评审发表。

诚征参展商/赞助商

大会将为电子封装及相关工业的材料、设备、组件、和软件供应商，制造商，及服务商提供参展平台，有意的参展商/赞助商请与大会通过电子邮件联系：icept2008@fudan.edu.cn

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